

Description

The AS358/358A/358B consists of two independent, high gain and internally frequency compensated operational amplifiers, they are specifically designed to operate from a single power supply. Operation from split power supply is also possible and the low power supply current drain is independent of the magnitude of the power supply voltages. Typical applications include transducer amplifiers, DC gain blocks and most conventional operational amplifier circuits.

The AS358/358A/358B series is compatible with industry standard 358. The AS358A has more stringent input offset voltage than the AS358.

The AS358 is available in DIP-8, TDIP-8, SOIC-8, TSSOP-8 and MSOP-8 packages, the AS358A is available in DIP-8 and SOIC-8 packages and AS358B is available in TSSOP-8 package.

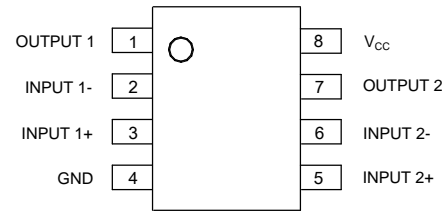
Features

- Internally Frequency Compensated for Unity Gain
- Large Voltage Gain: 100dB (Typical)
- Low Input Bias Current: 20nA (Typical)
- Low Input Offset Voltage: 2mV (Typical)
- Low Supply Current: 0.5mA (Typical)
- Wide Power Supply Voltage:
 - Single Supply: 3V to 36V
 - Dual Supplies: $\pm 1.5V$ to $\pm 18V$
- Input Common Mode Voltage Range Includes Ground
- Large Output Voltage Swing: 0V to $V_{CC} - 1.5V$
- Lead-Free Packages: SOIC-8, DIP-8, TSSOP-8 and MSOP-8
 - **Totally Lead-Free; RoHS Compliant (Notes 1 & 2)**
- Lead-Free Packages, Available in "Green" Molding Compound: SOIC-8, DIP-8, TDIP-8, TSSOP-8 and MSOP-8
 - **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
 - **Halogen and Antimony Free. "Green" Device (Note 3)**

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

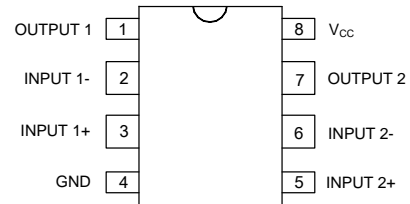
Pin Assignments

(Top View)



(SOIC-8/TSSOP-8/MSOP-8)

(Top View)



(DIP-8/TDIP-8)

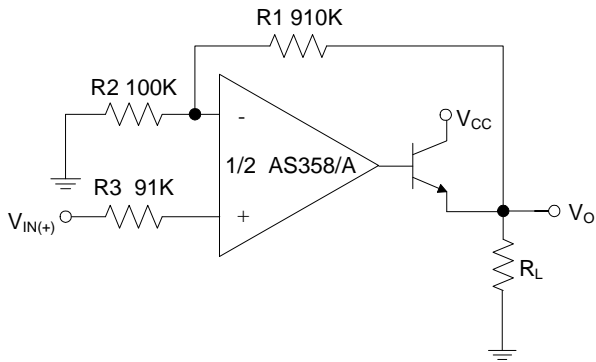
Applications

- Battery Charger
- Cordless Telephone
- Switching Power Supply

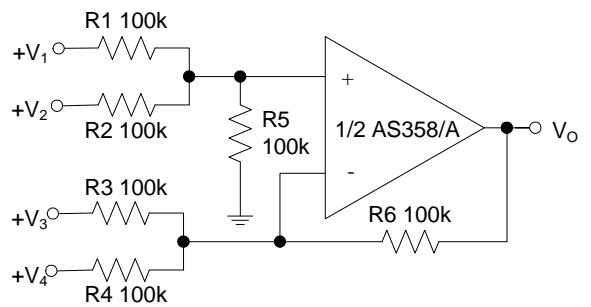
Typical Applications Circuit



Battery Charger

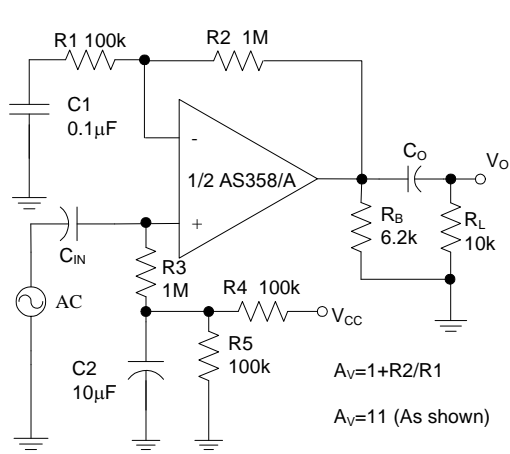


Power Amplifier

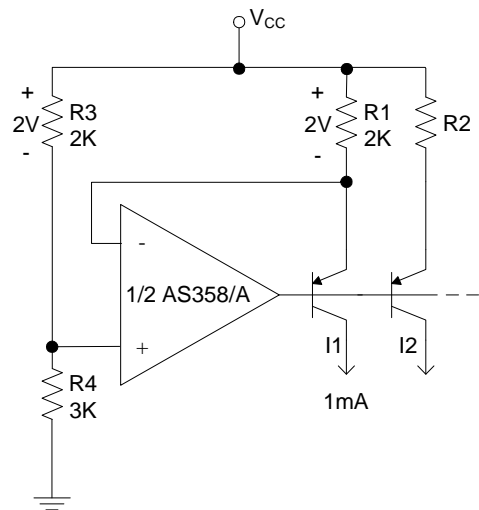


DC Summing Amplifier

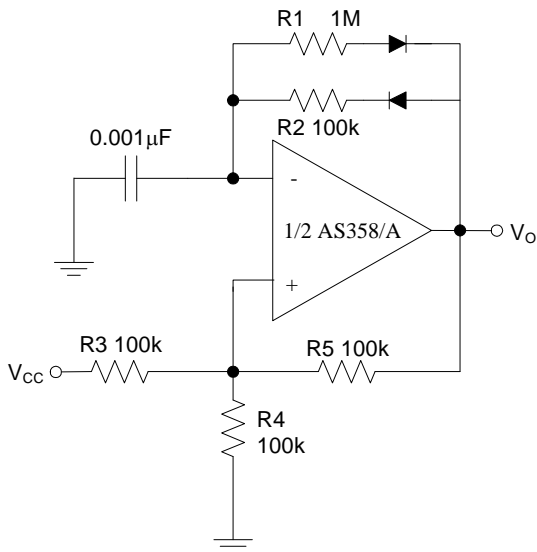
Typical Applications Circuit (Cont.)



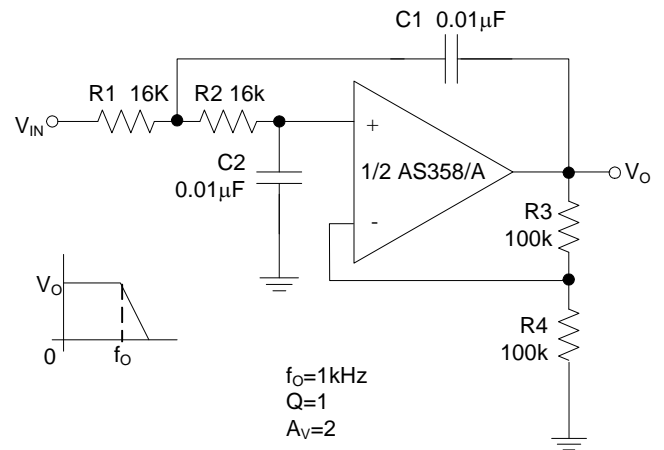
AC Coupled Non-Inverting Amplifier



Fixed Current Sources



Pulse Generator



DC Coupled Low-Pass Active Filter

Functional Block Diagram



Absolute Maximum Ratings (Notes 4 & 5)

Symbol	Parameter	Rating		Unit
V _{CC}	Power Supply Voltage	40		V
V _{ID}	Differential Input Voltage	40		V
V _{IC}	Input Voltage	-0.3 to 40		V
P _D	Power Dissipation (T _A = +25°C)	DIP-8	830	mW
		SOIC-8	550	
		TSSOP-8	500	
		MSOP-8	470	
T _J	Operating Junction Temperature	+150		°C
T _{STG}	Storage Temperature Range	-65 to +150		°C
T _{LEAD}	Lead Temperature (Soldering, 10 Seconds)	+260		°C

Notes: 4. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

5. ESD sensitivity.

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Unit
V _{CC}	Supply Voltage	3	36	V
T _A	Ambient Operating Temperature Range	-40	+85	°C

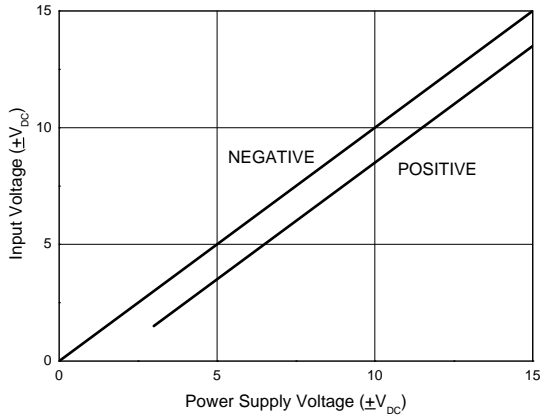
Electrical Characteristics (Limits in standard typeface are for $T_A = +25^\circ\text{C}$, **bold** typeface applies over -40°C to $+85^\circ\text{C}$ (Note 6), $V_{CC} = 5\text{V}$, $\text{GND} = 0\text{V}$, unless otherwise specified.)

Symbol	Parameter		Conditions	Min	Typ	Max	Unit	
V_{IO}	Input Offset Voltage		$V_O = 1.4\text{V}$, $R_S = 0\Omega$, $V_{CC} = 5\text{V to } 30\text{V}$	AS358	-	2	5	mV
					-	-	7	
				AS358A	-	2	3	
					-	-	5	
				AS358B	-	-	2	
					-	-	4	
$\Delta V_{IO}/\Delta T$	Average Temperature Coefficient of Input Offset Voltage		$T_A = -40^\circ\text{C to } +85^\circ\text{C}$	-	7	-	$\mu\text{V}/^\circ\text{C}$	
I_{BIAS}	Input Bias Current		I_{IN+} or I_{IN-} , $V_{CM} = 0\text{V}$	-	20	200	nA	
				-	-	200		
I_{IO}	Input Offset Current		$I_{IN+} - I_{IN-}$, $V_{CM} = 0\text{V}$	-	5	30	nA	
				-	-	100		
V_{IR}	Input Common Mode Voltage Range (Note 7)		$V_{CC} = 30\text{V}$	0	-	$V_{CC} - 1.5$	V	
I_{CC}	Supply Current		$T_A = -40^\circ\text{C to } +85^\circ\text{C}$, $R_L = \infty$, $V_{CC} = 30\text{V}$	-	0.7	2	mA	
			$T_A = -40^\circ\text{C to } +85^\circ\text{C}$, $R_L = \infty$, $V_{CC} = 5\text{V}$	-	0.5	1.2		
G_V	Large Signal Voltage Gain		$V_{CC} = 15\text{V}$, $V_O = 1\text{V to } 11\text{V}$, $R_L \geq 2\text{k}\Omega$	85	100	-	dB	
				80	-	-		
CMRR	Common Mode Rejection Ratio		DC, $V_{CM} = 0\text{V to } (V_{CC} - 1.5)\text{V}$	60	70	-	dB	
				60	-	-		
PSRR	Power Supply Rejection Ratio		$V_{CC} = 5\text{V to } 30\text{V}$	70	100	-	dB	
				60	-	-		
CS	Channel Separation		$f = 1\text{kHz to } 20\text{kHz}$	-	-120	-	dB	
I_{SOURCE}	Output Current	Source	$V_{IN+} = 1\text{V}$, $V_{IN-} = 0\text{V}$, $V_{CC} = 15\text{V}$, $V_O = 2\text{V}$	20	40	-	mA	
		Sink	$V_{IN+} = 0\text{V}$, $V_{IN-} = 1\text{V}$, $V_{CC} = 15\text{V}$, $V_O = 2\text{V}$	20	-	-		
I_{SINK}	Output Current	Sink	$V_{IN+} = 0\text{V}$, $V_{IN-} = 1\text{V}$, $V_{CC} = 15\text{V}$, $V_O = 2\text{V}$	10	15	-	mA	
			$V_{IN+} = 0\text{V}$, $V_{IN-} = 1\text{V}$, $V_{CC} = 15\text{V}$, $V_O = 0.2\text{V}$	5	-	-		
I_{SC}	Output Short Circuit Current to Ground		$V_{CC} = 15\text{V}$	-	40	60	mA	
				-	-	-		
V_{OH}	Output Voltage Swing		$V_{CC} = 30\text{V}$, $R_L = 2\text{k}\Omega$	26	-	-	V	
				26	-	-		
			$V_{CC} = 30\text{V}$, $R_L = 10\text{k}\Omega$	27	28	-		
V_{OL}			$V_{CC} = 5\text{V}$, $R_L = 10\text{k}\Omega$	-	5	20	mV	
				-	-	30		
θ_{JC}	Thermal Resistance (Junction to Case)		DIP-8	-	53	-	$^\circ\text{C}/\text{W}$	
			SOIC-8	-	78	-		

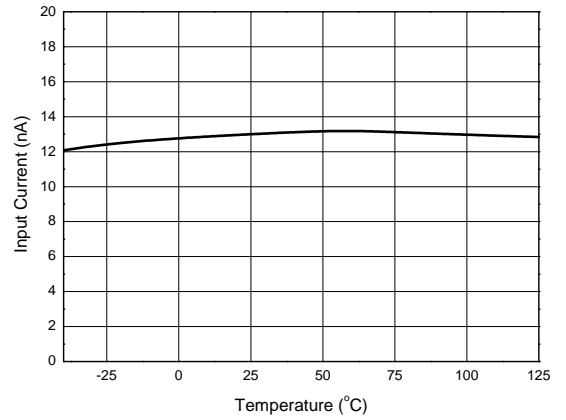
Notes: 6. Limits over the full temperature are guaranteed by design, but not tested in production.
7. The input common-mode voltage of either input signal voltage should not be allowed to go negatively by more than 0.3V (at $+25^\circ\text{C}$). The upper end of the common-mode voltage range is $V_{CC} - 1.5\text{V}$ (at $+25^\circ\text{C}$), but either or both inputs can go to $+36\text{V}$ without damages, independent of the magnitude of the V_{CC} .

Performance Characteristics

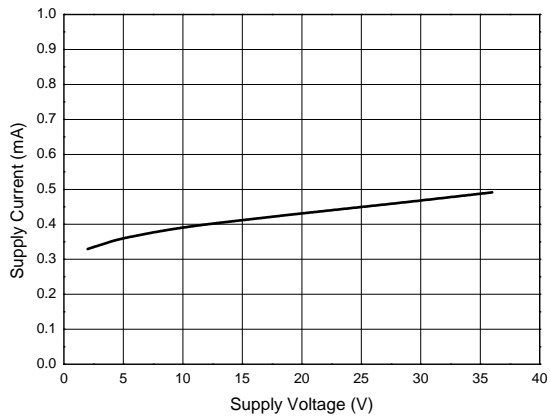
Input Voltage Range



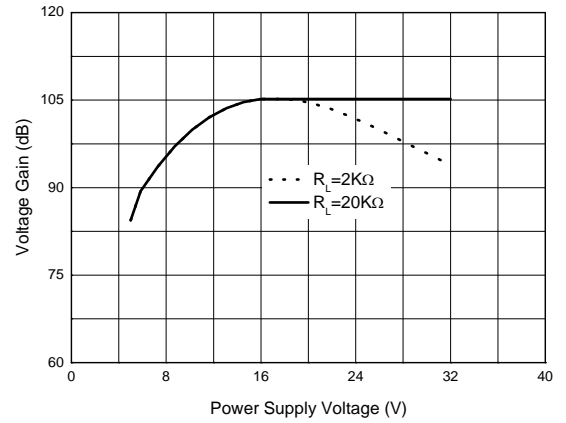
Input Current



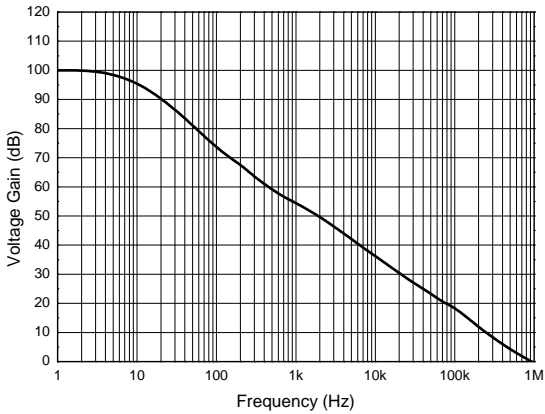
Supply Current



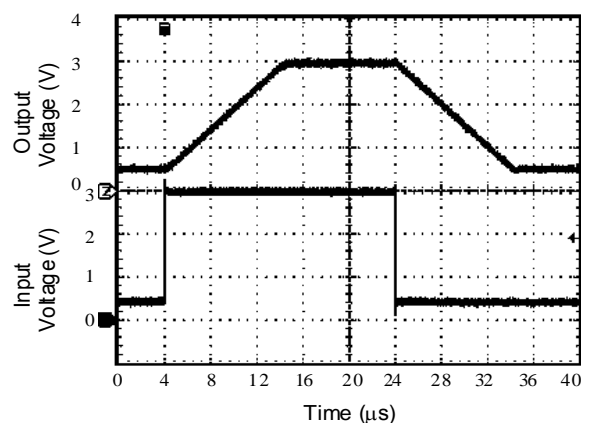
Voltage Gain



Open Loop Frequency Response



Voltage Follower Pulse Response

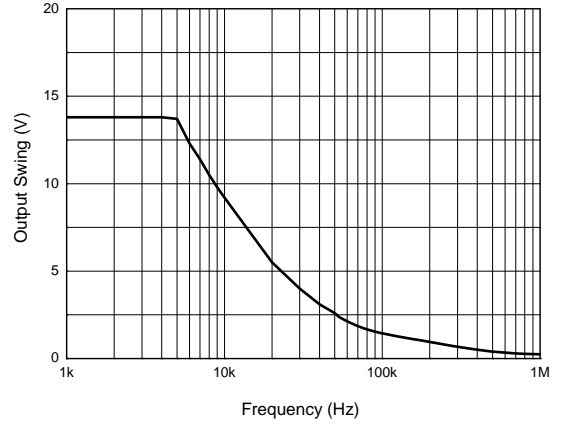


Performance Characteristics (Cont.)

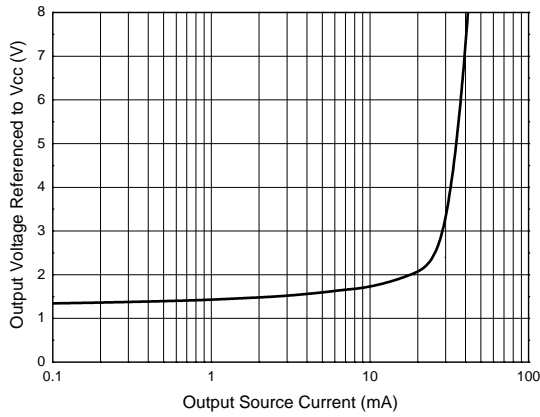
Voltage Follower Pulse Response (Small Signal)



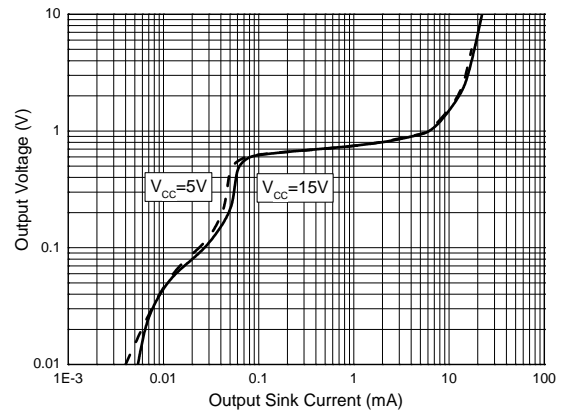
Large Signal Frequency Response



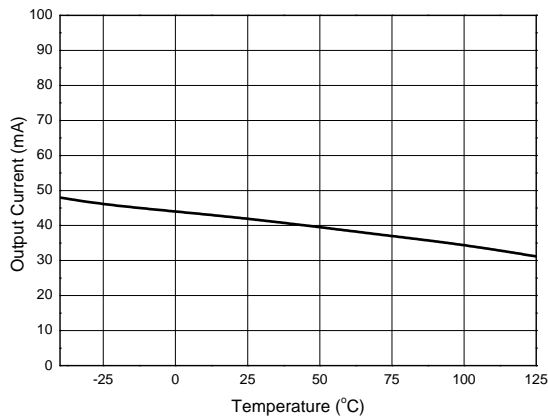
Output Characteristics: Current Sourcing



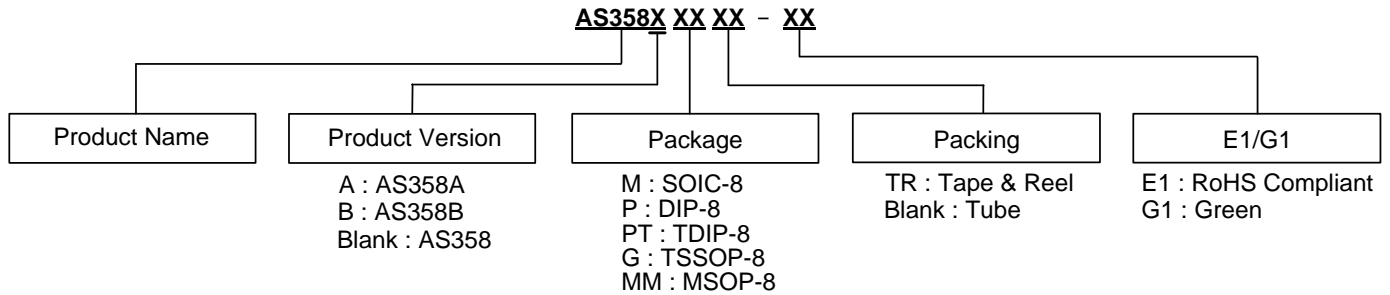
Output Characteristics: Current Sinking



Current Limiting



Ordering Information

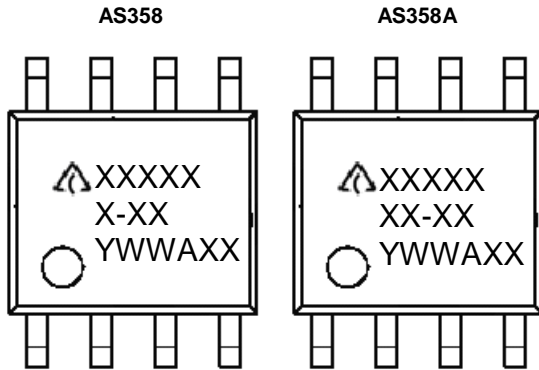


Package	Temperature Range	Part Number		Marking ID		Packing
		RoHS Compliant	Green	RoHS Compliant	Green	
SOIC-8	-40°C to +85°C	AS358M-E1	AS358M-G1	AS358M-E1	AS358M-G1	100/Tube
		AS358MTR-E1	AS358MTR-G1	AS358M-E1	AS358M-G1	4000/Tape & Reel
		AS358AM-E1	AS358AM-G1	AS358AM-E1	AS358AM-G1	100/Tube
		AS358AMTR-E1	AS358AMTR-G1	AS358AM-E1	AS358AM-G1	4000/Tape & Reel
DIP-8		AS358P-E1	AS358P-G1	AS358P-E1	AS358P-G1	50/Tube
		AS358AP-E1	AS358AP-G1	AS358AP-E1	AS358AP-G1	50/Tube
TDIP-8		-	AS358PT-G1	-	AS358PT-G1	50/Tube
TSSOP-8		AS358GTR-E1	AS358GTR-G1	EG3A	GG3A	4000/Tape & Reel
		-	AS358BGTR-G1	-	GG3F	4000/Tape & Reel
MSOP-8		AS358MMTR-E1	AS358MMTR-G1	AS358MM-E1	AS358MM-G1	3000/Tape & Reel



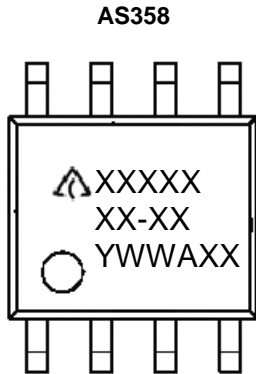
Marking Information

(1) SOIC-8



First and Second Lines: Logo and Marking ID
 Third Line: Date Code
 Y: Year
 WW: Work Week of Molding
 A: Assembly House Code
 XX: Internal Code

(2) MSOP-8



First and Second Lines: Logo and Marking ID
 Third Line: Date Code
 Y: Year
 WW: Work Week of Molding
 A: Assembly House Code
 XX: Internal Code

(3) DIP-8



First Line: Logo and Marking ID
 Second Line: Date Code
 Y: Year
 WW: Work Week of Molding
 A: Assembly House Code
 XX: Internal Code

Marking Information (Cont.)

(4) TDIP-8



First Line: Logo and Marking ID
 Second Line: Date Code
 Y: Year
 WW: Work Week of Molding
 A: Assembly House Code
 XX: Internal Code

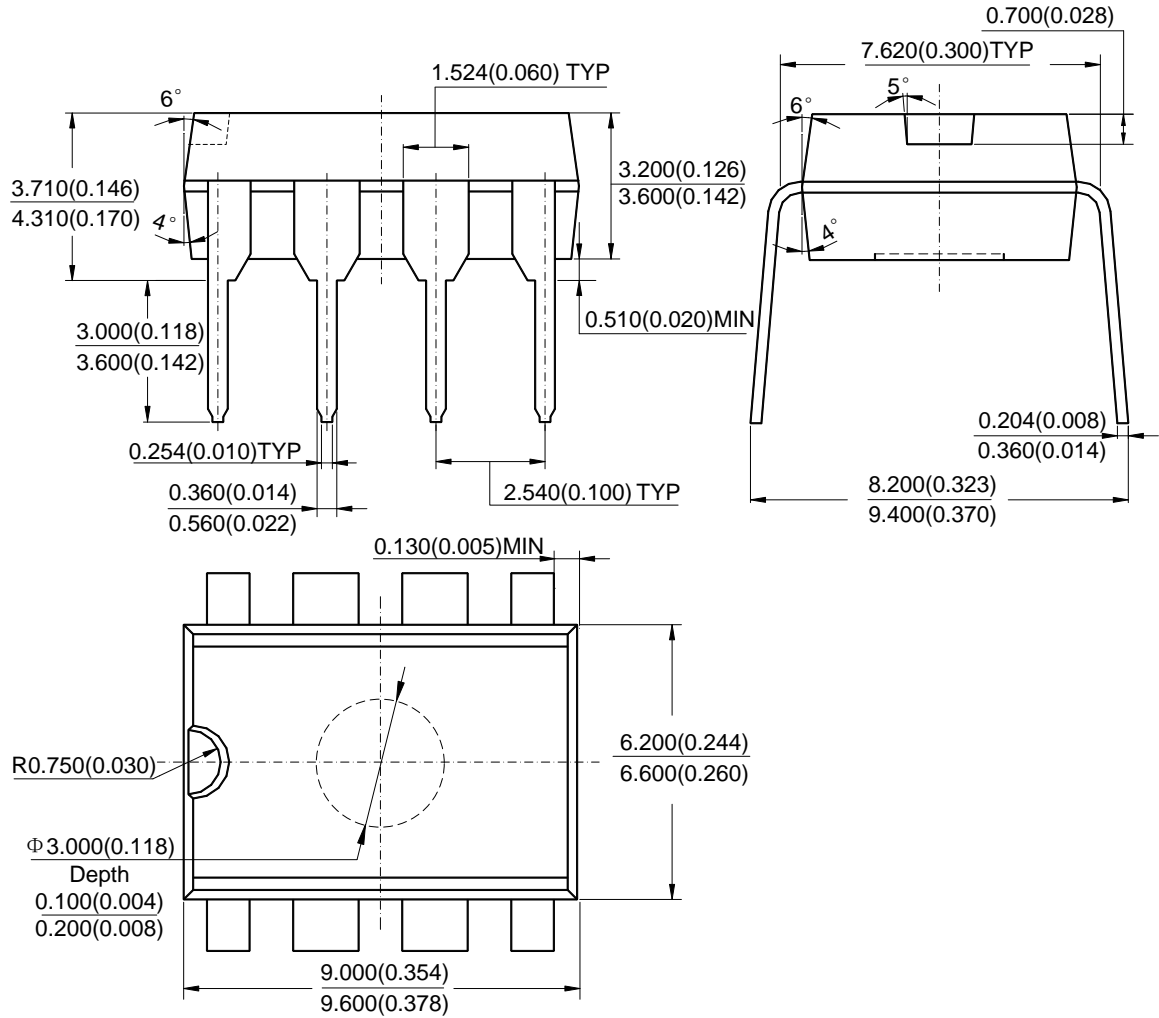
(5) TSSOP-8



First Line: Logo
 Second Line: Marking ID
 Third and Fourth Lines: Date Code
 Y: Year
 WW: Work Week of Molding
 A: Assembly House Code
 XX: Internal Code

Package Outline Dimensions (All dimensions in mm(inch).)

(1) Package Type: DIP-8



Note: Eject hole, oriented hole and mold mark is optional.

Package Outline Dimensions (Cont. All dimensions in mm(inch).)

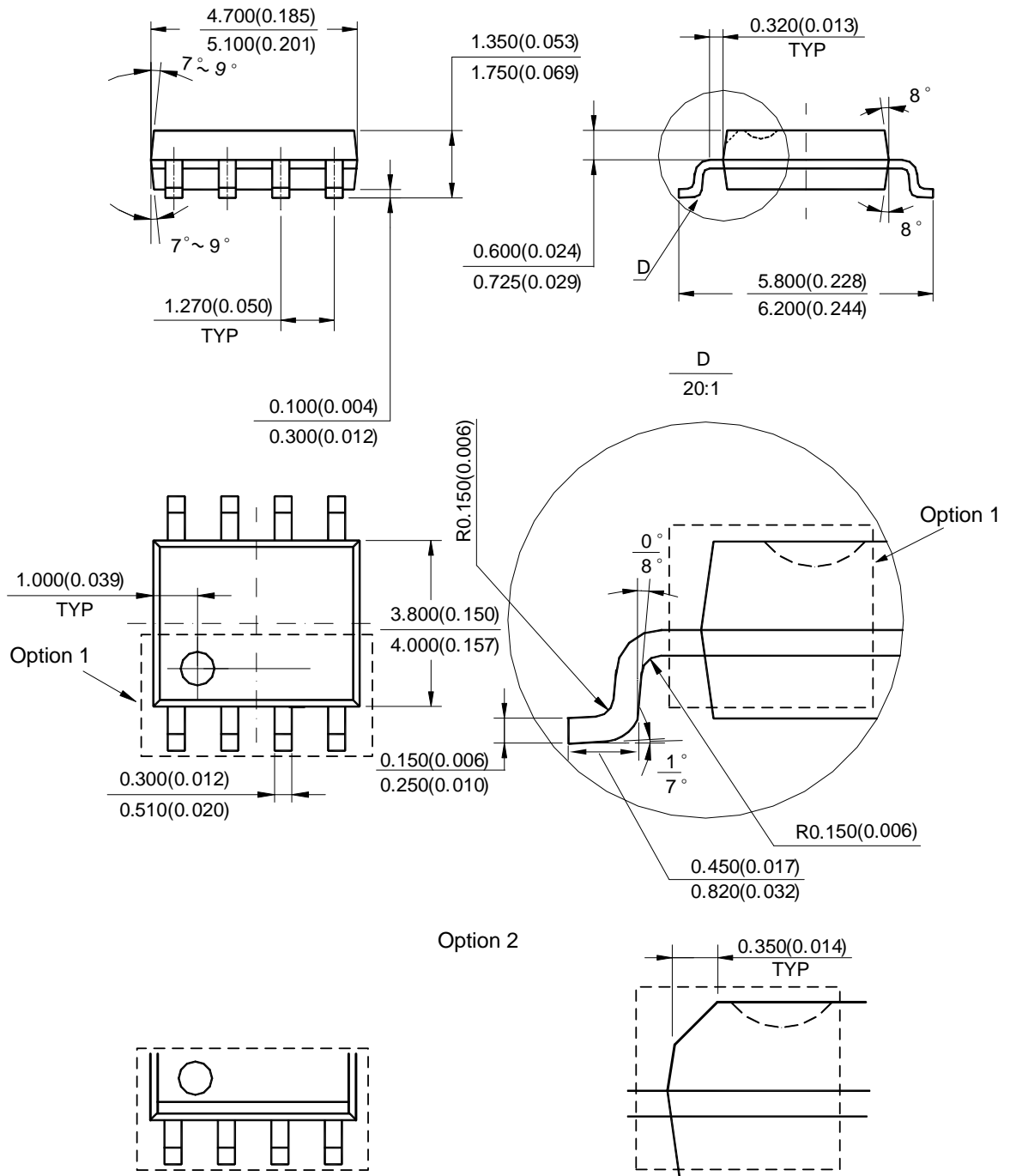
(2) Package Type: TDIP-8



Note: Eject hole, oriented hole and mold mark is optional.

Package Outline Dimensions (Cont. All dimensions in mm(inch).)

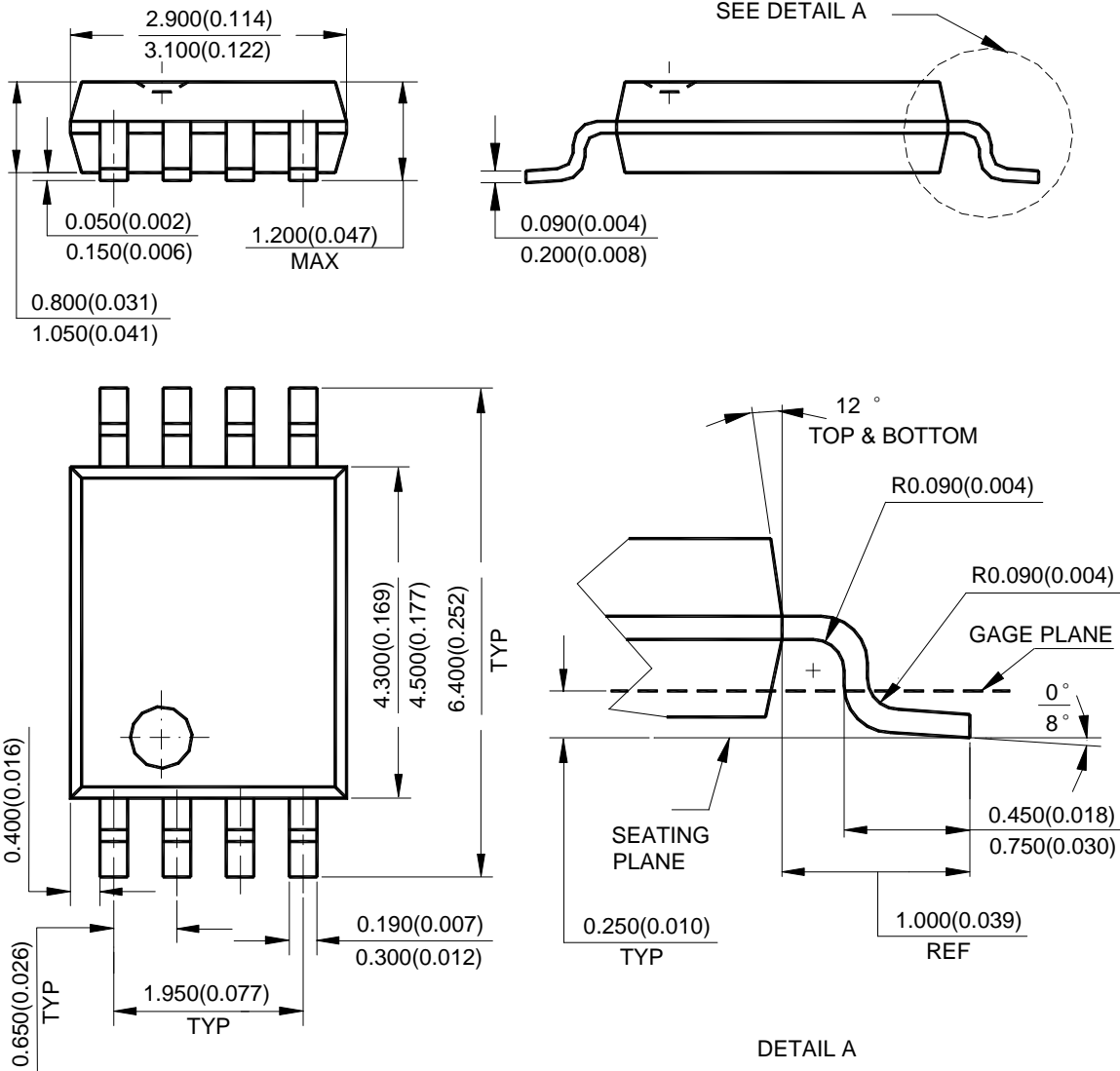
(3) Package Type: SOIC-8



Note: Eject hole, oriented hole and mold mark is optional.

Package Outline Dimensions (Cont. All dimensions in mm(inch).)

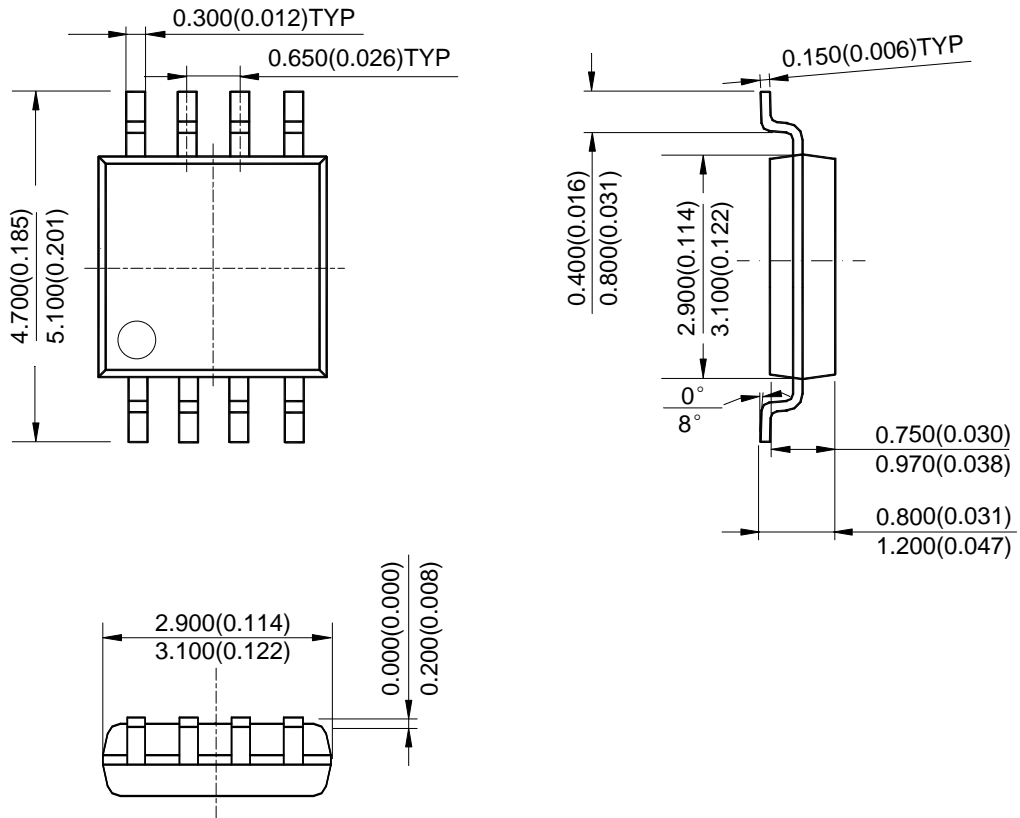
(4) Package Type: TSSOP-8



Note: Eject hole, oriented hole and mold mark is optional.

Package Outline Dimensions (Cont. All dimensions in mm(inch).)

(5) Package Type: MSOP-8



Note: Eject hole, oriented hole and mold mark is optional.

Suggested Pad Layout

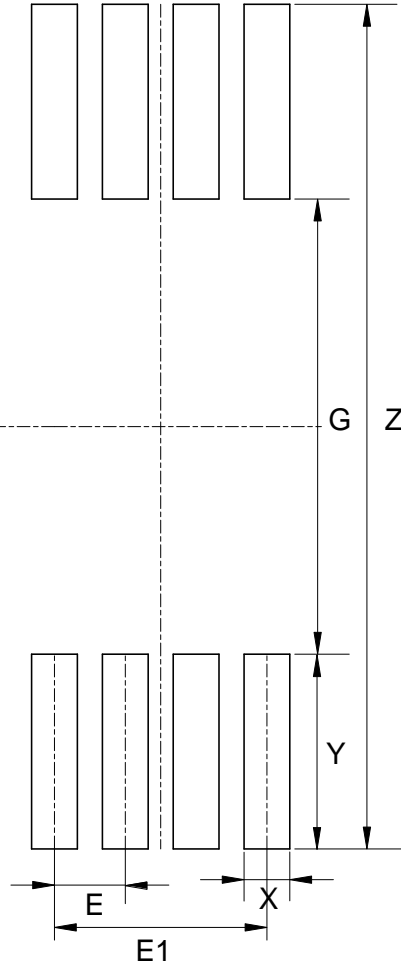
(1) Package Type: SOIC-8



Dimensions	Z (mm)/(inch)	G (mm)/(inch)	X (mm)/(inch)	Y (mm)/(inch)	E (mm)/(inch)
Value	6.900/0.272	3.900/0.154	0.650/0.026	1.500/0.059	1.270/0.050

Suggested Pad Layout (Cont.)

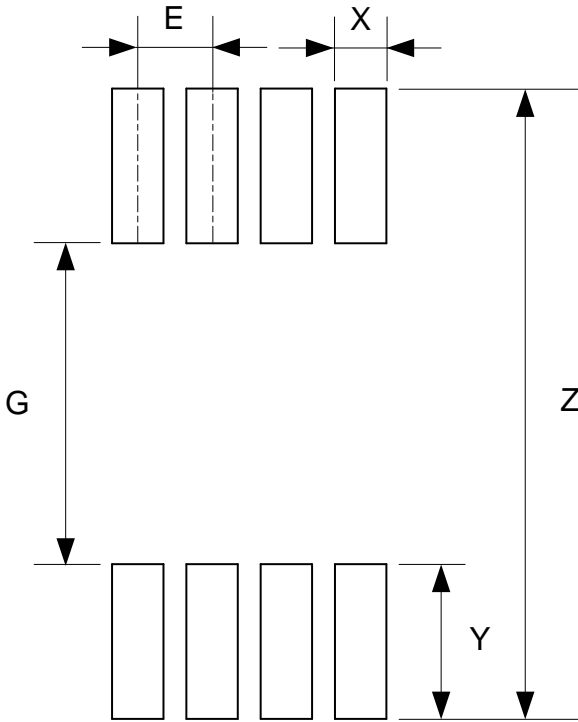
(2) Package Type: TSSOP-8



Dimensions	Z (mm)/(inch)	G (mm)/(inch)	X (mm)/(inch)	Y (mm)/(inch)	E (mm)/(inch)	E1 (mm)/(inch)
Value	7.720/0.304	4.160/0.164	0.420/0.017	1.780/0.070	0.650/0.026	1.950/0.077

Suggested Pad Layout (Cont.)

(3) Package Type: MSOP-8



Dimensions	Z (mm)/(inch)	G (mm)/(inch)	X (mm)/(inch)	Y (mm)/(inch)	E (mm)/(inch)
Value	5.500/0.217	2.800/0.110	0.450/0.018	1.350/0.053	0.650/0.026

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